

## IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Original): A molding method for manufacturing a resin molding by charging a resin composition including fibrous filler (A) and resin (B) in molten state into a die by injection, wherein the resin composition contains not less than 7 wt% to less than 30 wt% of the fibrous filler (A) and more than 70 wt% to not exceeding 93 wt% of the resin (B),

and that comprises the steps of;

(a) charging the resin composition in molten state into the die for shaping purpose when a temperature of the die is in the range of [the Vicat softening point minus 20°C] of the resin (B) to less than a melting point thereof, when the resin (B) is crystalline resin,

or charging the resin composition in molten state into the die for shaping purpose when a temperature of the die is in the range of [the Vicat softening point minus 20°C] to [the Vicat softening point plus 20°C] of the resin (B), when the resin (B) is non-crystalline resin; and

(b) cooling down the die to a temperature which allows taking-out of a molded product, after the shaping is performed.

Claim 2 (Original): A molding method for manufacturing a resin molding by extruding a resin composition including fibrous filler (A) and resin (B) to be converted into a molten parison, holding the parison within a die, and by blowing gas into the parison inside, wherein the resin composition contains more than 7 wt% to less than 30 wt% of the fibrous filler (A) and more than 70 wt% to less than 93 wt% of the resin (B),

and that comprises the steps of;

(a) blowing gas into the parison inside for shaping purpose when a temperature of the die is in the range of [the Vicat softening point minus 20°C] of the resin (B) to less than a melting point thereof, when the resin (B) is crystalline resin,

or blowing a gas into the parison inside for shaping purpose when a temperature of the die is in the range of [the Vicat softening point minus 20°C] to [the Vicat softening point plus 20°C] of the resin (B), when the resin (B) is non-crystalline resin; and

(b) cooling down the die to temperature which allows taking-out of a molded product after the shaping is performed

Claim 3 (Currently Amended): The molding method according to Claim 1 ~~or Claim 2~~, wherein if the resin (B) is crystalline resin, after shaping of the resin composition is performed, a temperature of the die is held for preset period in the range of [crystallization temperature minus 15°C] to [crystallization temperature plus 10°C] of the resin (B).

Claims 4-10 (Canceled).

Claim 11 (New): The molding method according to Claim 2, wherein if the resin (B) is crystalline resin, after shaping of the resin composition is performed, a temperature of the die is held for preset period in the range of [crystallization temperature minus 15°C] to [crystallization temperature plus 10°C] of the resin (B).

Claim 12 (New): The molding method according to Claim 1, wherein shaping of the resin composition is performed when a temperature of the die is in the range of [the Vicat

softening temperature minus 10°C] of the resin (B) to [melting point minus 10°C], when the resin (B) is crystalline resin,

or performed when a temperature of the die is in the range of [the Vicat softening temperature minus 10°C] to [the Vicat softening temperature plus 10°C] of the resin (B), when the resin (B) is non-crystalline resin.

Claim 13 (New): The molding method according to Claim 2, wherein shaping of the resin composition is performed when a temperature of the die is in the range of [the Vicat softening temperature minus 10°C] of the resin (B) to [melting point minus 10°C], when the resin (B) is crystalline resin,

or performed when a temperature of the die is in the range of [the Vicat softening temperature minus 10°C] to [the Vicat softening temperature plus 10°C] of the resin (B), when the resin (B) is non-crystalline resin.

Claim 14 (New): The molding method according to Claim 1, wherein after shaping of the resin composition is performed, a temperature of the die is held for preset period in the range of [crystallization temperature minus 10°C] to [crystallization temperature] of the resin (B), when the resin (B) is crystalline resin.

Claim 15 (New): The molding method according to Claim 2, wherein after shaping of the resin composition is performed, a temperature of the die is held for preset period in the range of [crystallization temperature minus 10°C] to [crystallization temperature] of the resin (B), when the resin (B) is crystalline resin.

Claim 16 (New): The molding method according to Claim 1, wherein the resin composition contains not less than 10 wt% to not exceeding 25 wt% of the fibrous filler (A).

Claim 17 (New): The molding method according to Claim 2, wherein the resin composition contains not less than 10 wt% to not exceeding 25 wt% of the fibrous filler (A).

Claim 18 (New): A resin molding manufactured by the molding method of Claim 1.

Claim 19 (New): A resin molding manufactured by the molding method of Claim 2.

Claim 20 (New): A resin molding containing not less than 7 wt% to less than 30 wt% of a fibrous fiber (A) and more than 70 wt% to not exceeding 93 wt% of a resin (B), wherein surface roughness is less than 5  $\mu\text{m}$  and an image representation of 1 mm square rectangular frame reflected on the surface can be discriminated.

Claim 21 (New): A resin molding having an emboss on the surface and containing not less than 7 wt% to less than 30 wt% of a fibrous fiber (A) and more than 70 wt% to not exceeding 93 wt% of a resin (B), and is characterized by either one of the following 1 or 2.

(1) Die transcription rate is more than 90% for such a case where emboss is provided over whole surface of a resin molding;

(2) Die transcription rate is more than 90% and surface roughness of such an area where there is no emboss is less than 5  $\mu\text{m}$  for such a case where emboss is provided in part of a resin molding.

Claim 22 (New): The resin molding according to Claim 20, wherein the resin composition contains not less than 10 wt% to not exceeding to 25 wt% of the fibrous filler (A).

Claim 23 (New): The resin molding according to Claim 21, wherein the resin composition contains not less than 10 wt% to not exceeding to 25 wt% of the fibrous filler (A).